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(12) **United States Design Patent**
Kanda et al.

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(45) **Date of Patent:** **** Jan. 21, 2020**

(54) **SEMICONDUCTOR MODULE**

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(**) Term: **15 Years**

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(30) **Foreign Application Priority Data**

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(51) **LOC (12) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/182**

(58) **Field of Classification Search**
USPC D13/182

(Continued)

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(57) **CLAIM**

The ornamental design for a semiconductor module, as shown and described.

DESCRIPTION

FIG. 1 is a front, top and right side perspective view of a first embodiment of a semiconductor module showing our new design;

FIG. 2 is a rear, bottom, and left side perspective view thereof;

FIG. 3 is a front view, the rear view being identical to FIG. 3;

FIG. 4 is a top plan view thereof;

FIG. 5 is a bottom plan view thereof;

FIG. 6 is a right side view thereof;

FIG. 7 is a left side view thereof;

FIG. 8 is a cross-sectional view taken along line 8-8 in FIG. 4;

FIG. 9 is a cross-sectional view taken along line 9-9 in FIG. 4;

FIG. 10 is a front, top and right side perspective view of a second embodiment of a semiconductor module showing our new design;

FIG. 11 is a rear, bottom, and left side perspective view thereof;

FIG. 12 is a front view, the rear view being identical to FIG. 12;

FIG. 13 is a top plan view thereof;

FIG. 14 is a bottom plan view thereof;

FIG. 15 is a right side view thereof;

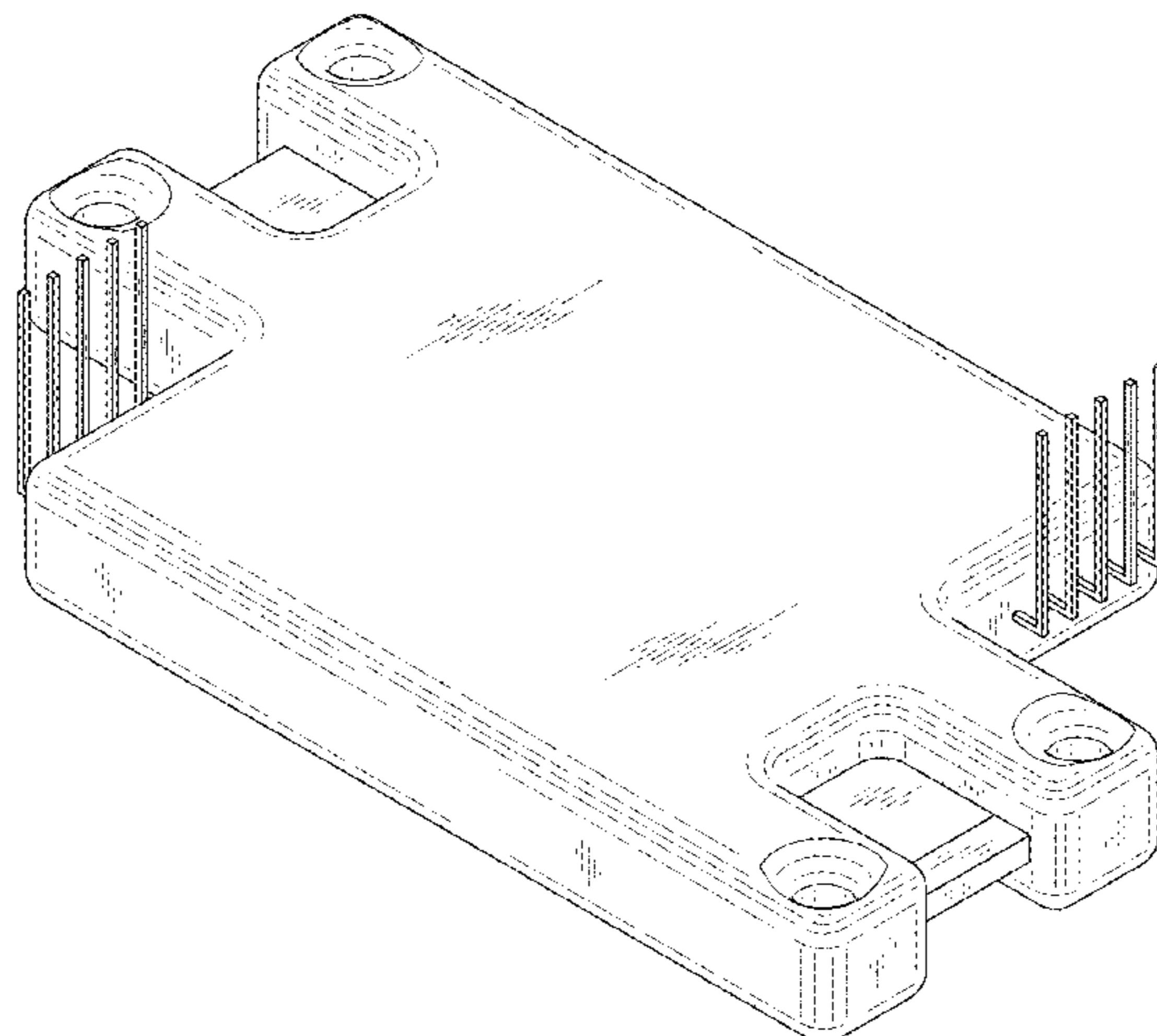
FIG. 16 is a left side view thereof;

FIG. 17 is a cross-sectional view taken along line 17-17 in FIG. 13; and,

FIG. 18 is a cross-sectional view taken along line 18-18 in FIG. 13.

The member illustrated with fine, diagonal, parallel lines in FIG. 2 and FIG. 5 is translucent.

1 Claim, 14 Drawing Sheets



(58) **Field of Classification Search**

CPC H01L 21/02428; H01L 21/0243; H01L
21/02494; H01L 21/02496; H01L
21/02499; H01L 21/02502; H01L
21/02505; H01L 21/02507; H01L
21/0251; H01L 21/02513; H01L
21/02587; H01L 21/0259; H01L
21/02592; H01L 21/02595; H01L
21/02598; H01L 21/02603; H01L
21/02606; H01L 23/04; H01L 23/041;
H01L 23/043; H01L 23/045; H01L
23/047; H01L 23/049; H01L 23/051;
H01L 23/053; H01L 23/055; H01L
23/057; H01L 23/06; H01L 23/08; H01L
23/10; H01L 23/452; H01L 23/4922;
H01L 29/02; H01L 29/04; H01L 29/045;
H01L 29/06; H01L 29/0603; H01L
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See application file for complete search history.

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D717,256	S	*	11/2014	Sohn	D13/182
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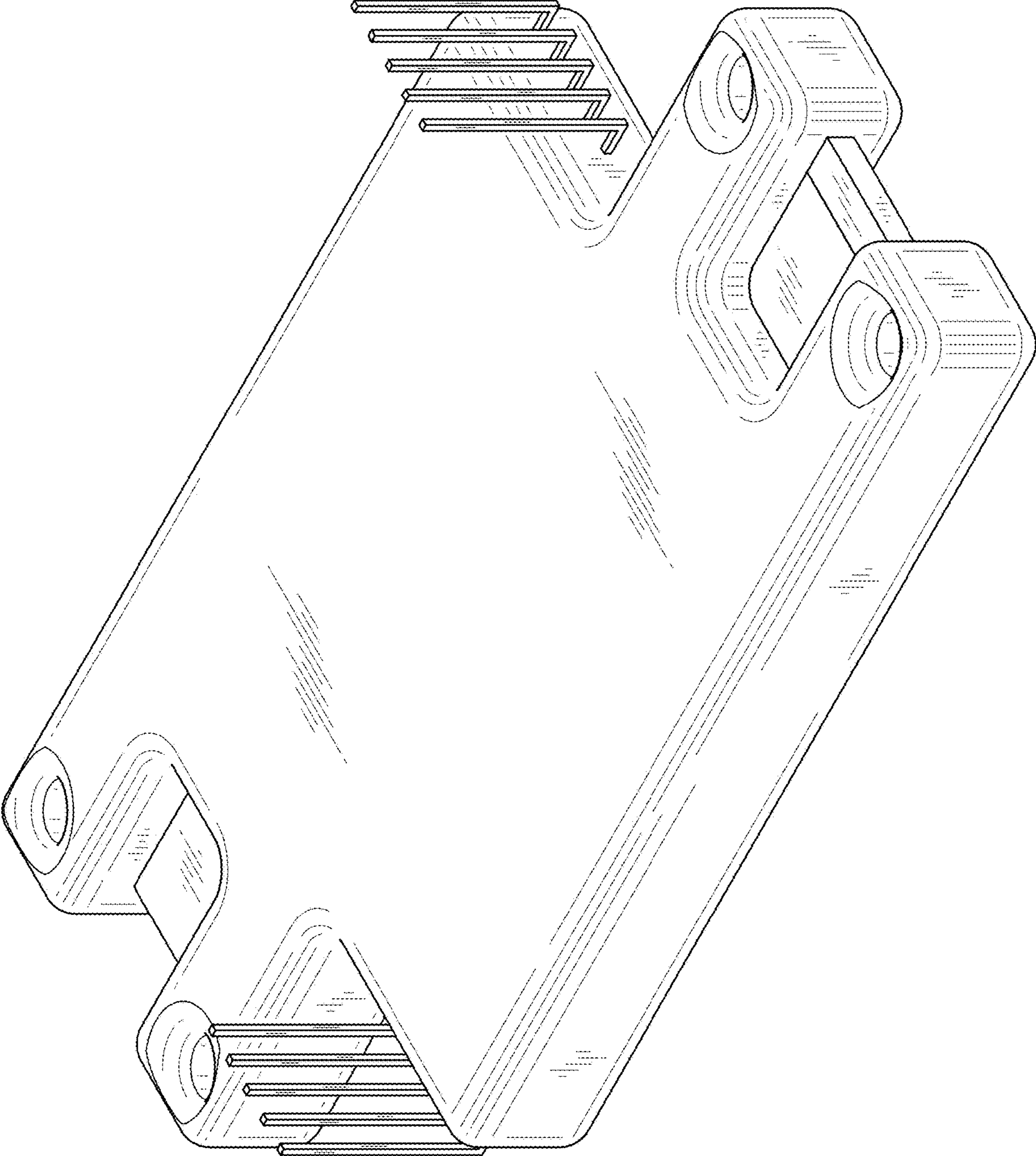


FIG.1

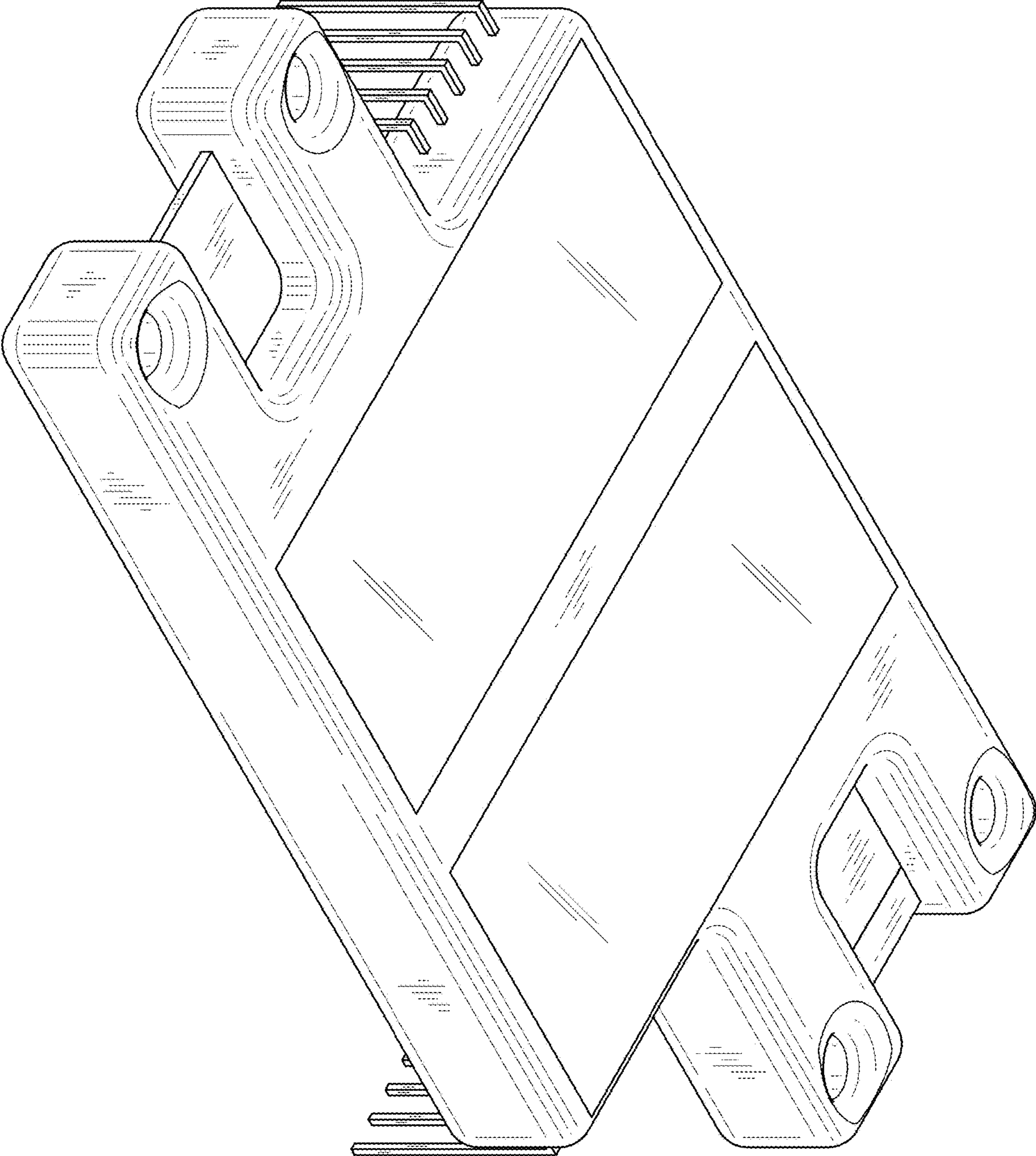


FIG.2

FIG.3

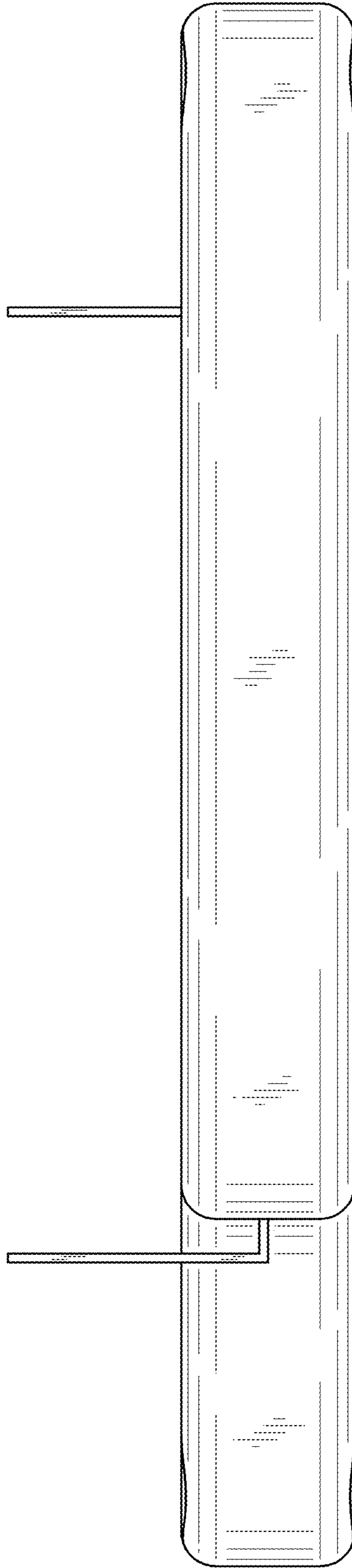
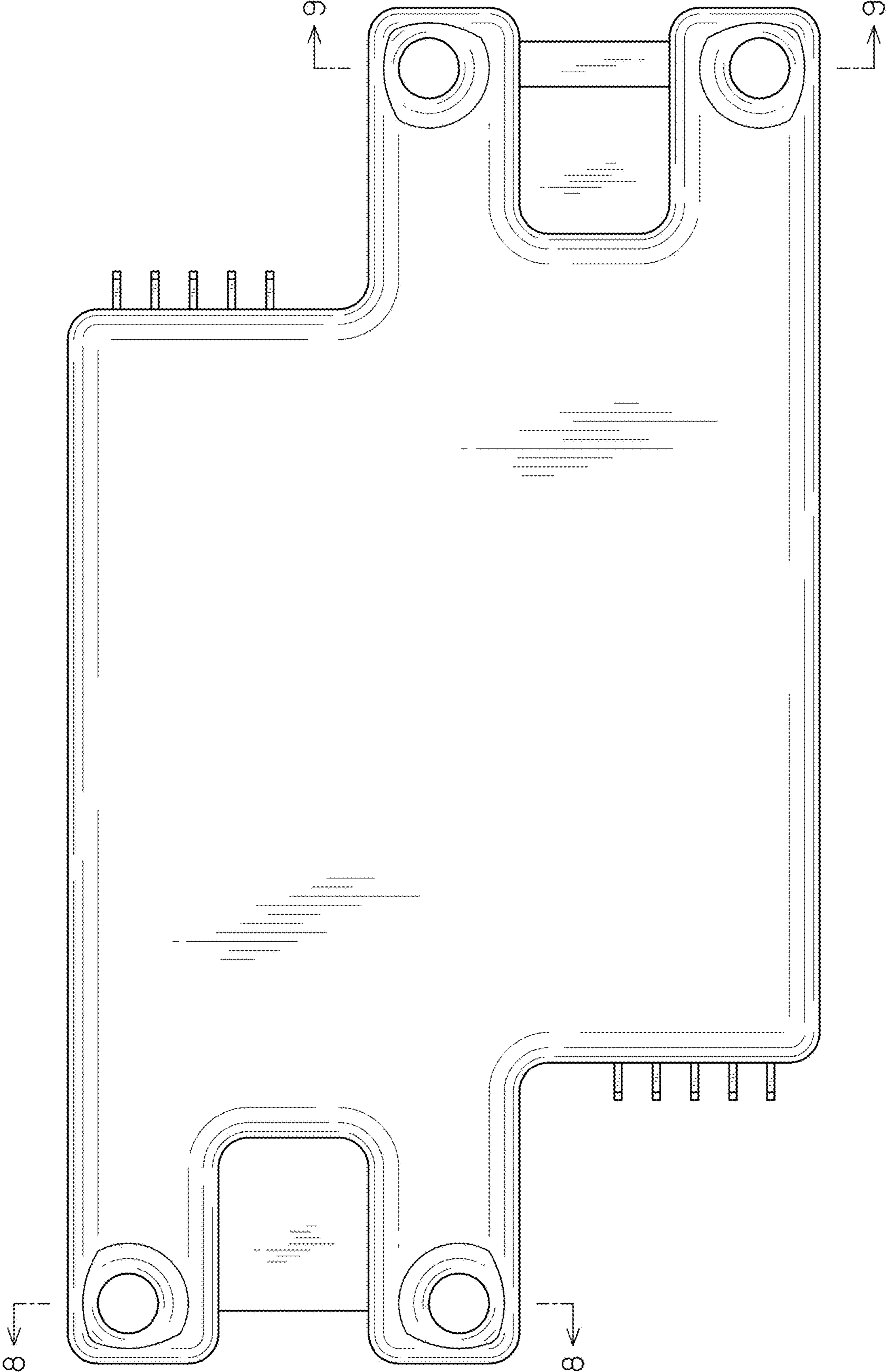


FIG.4



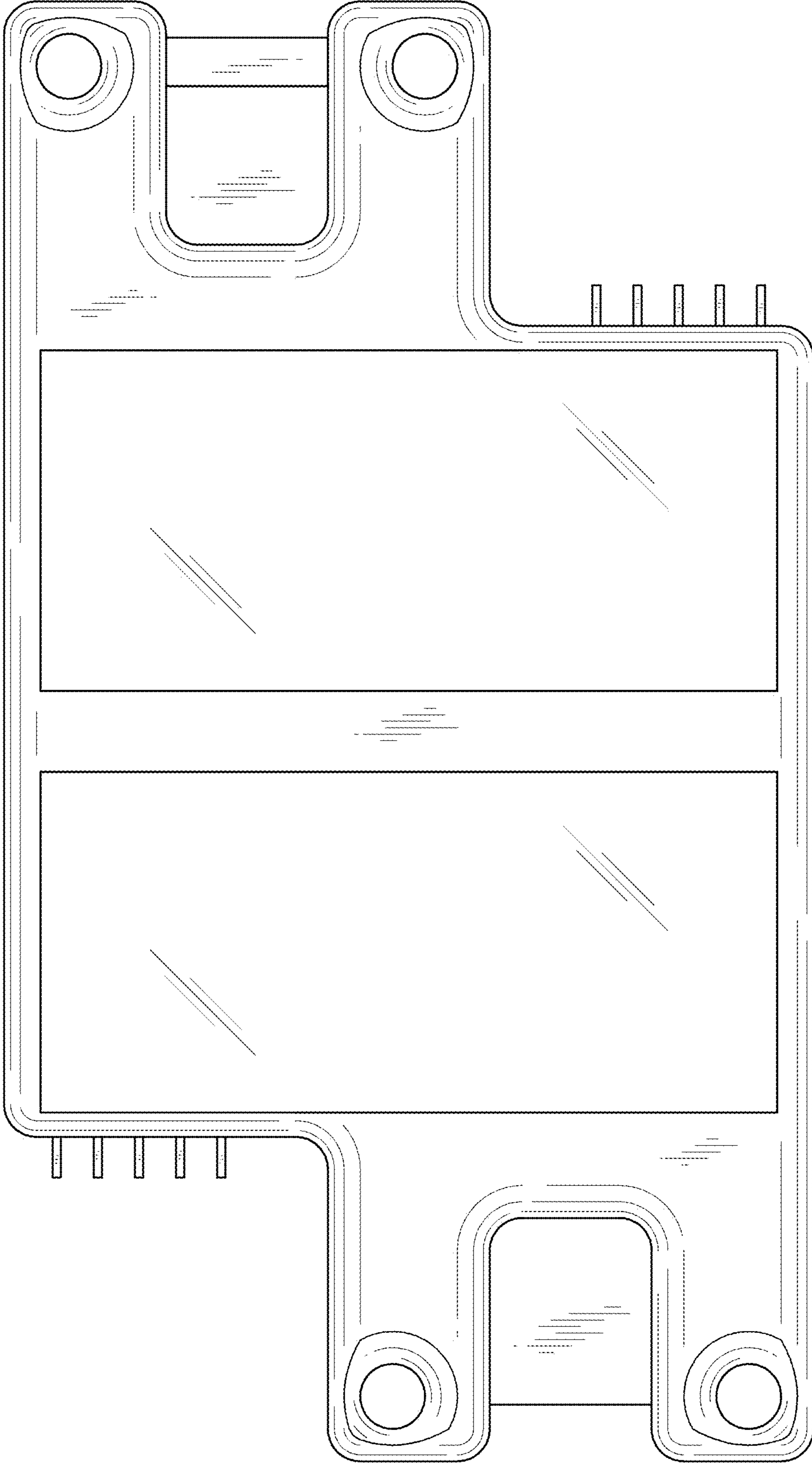


FIG.5

FIG.6

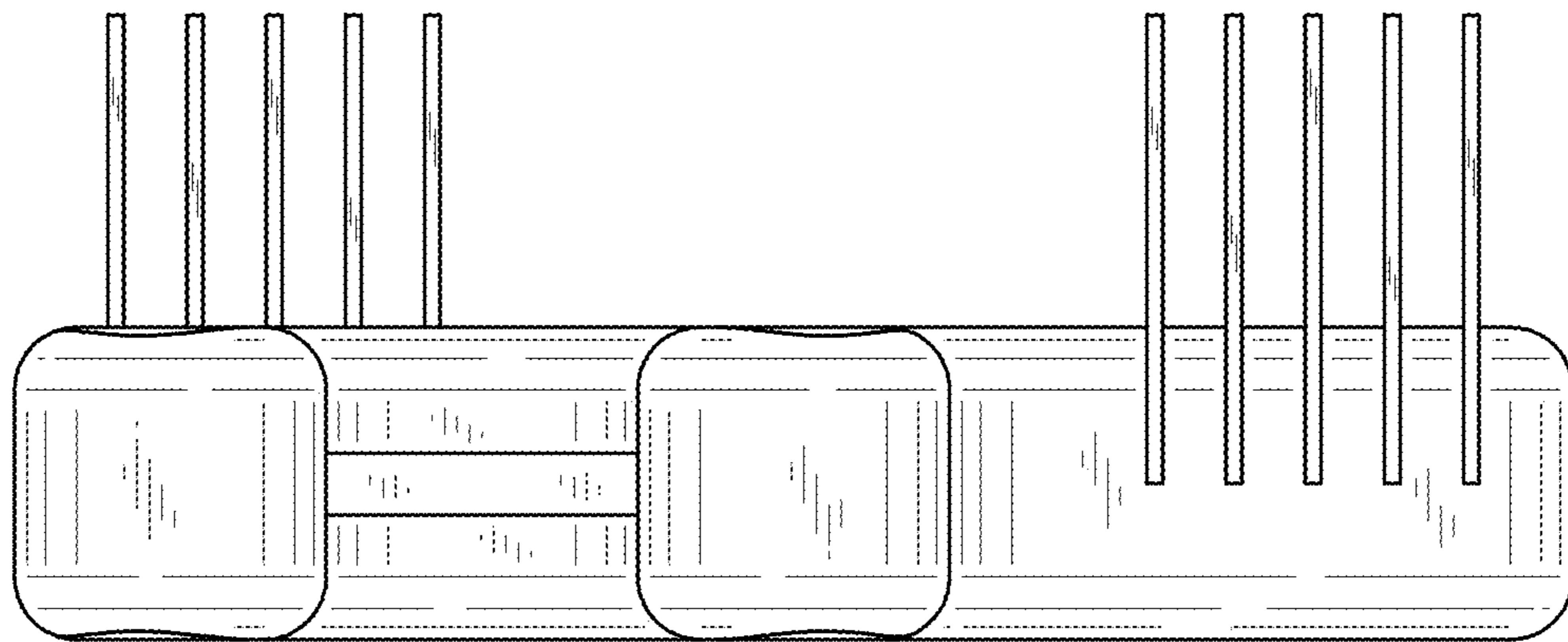


FIG.7

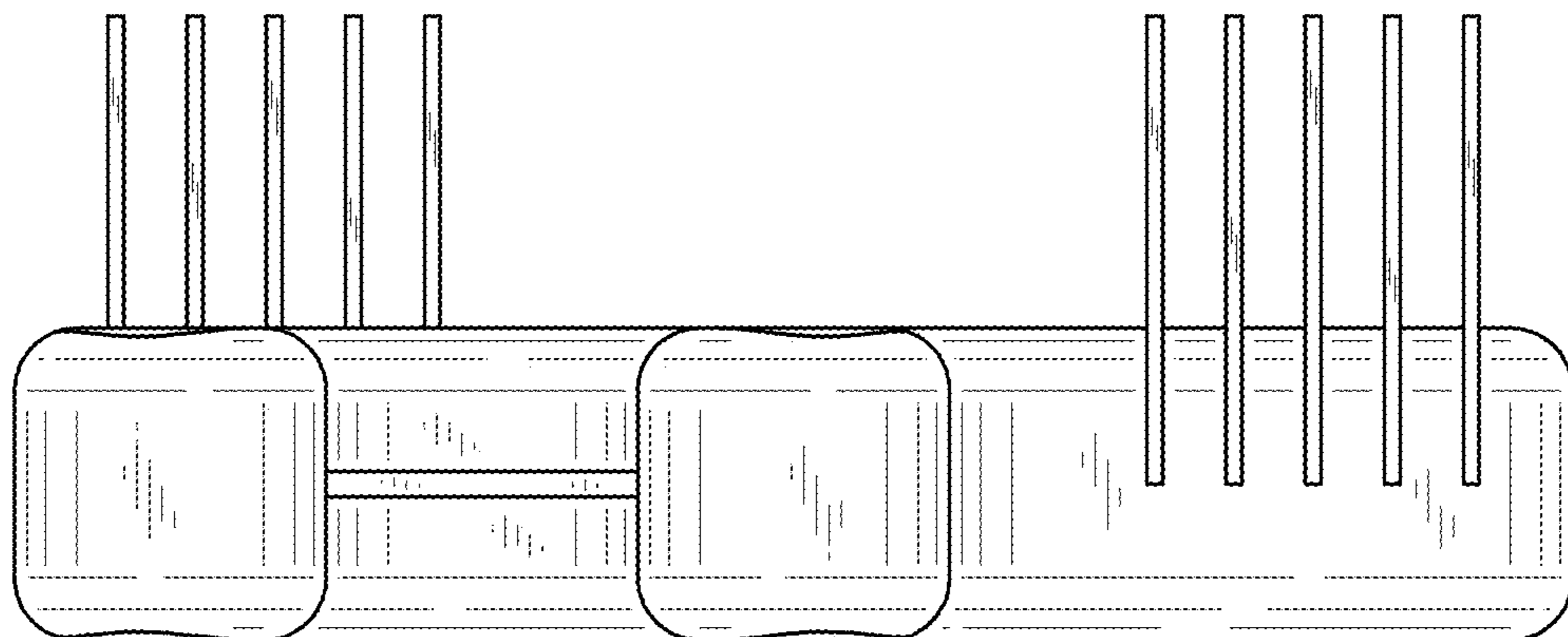


FIG.8

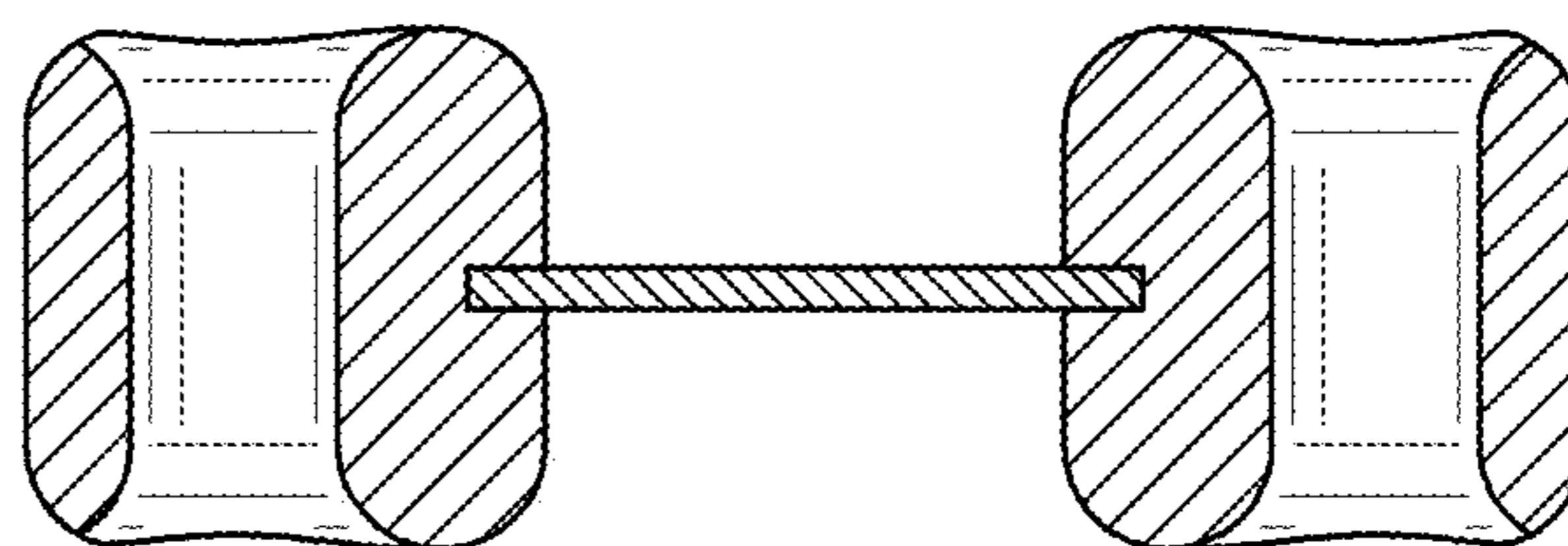
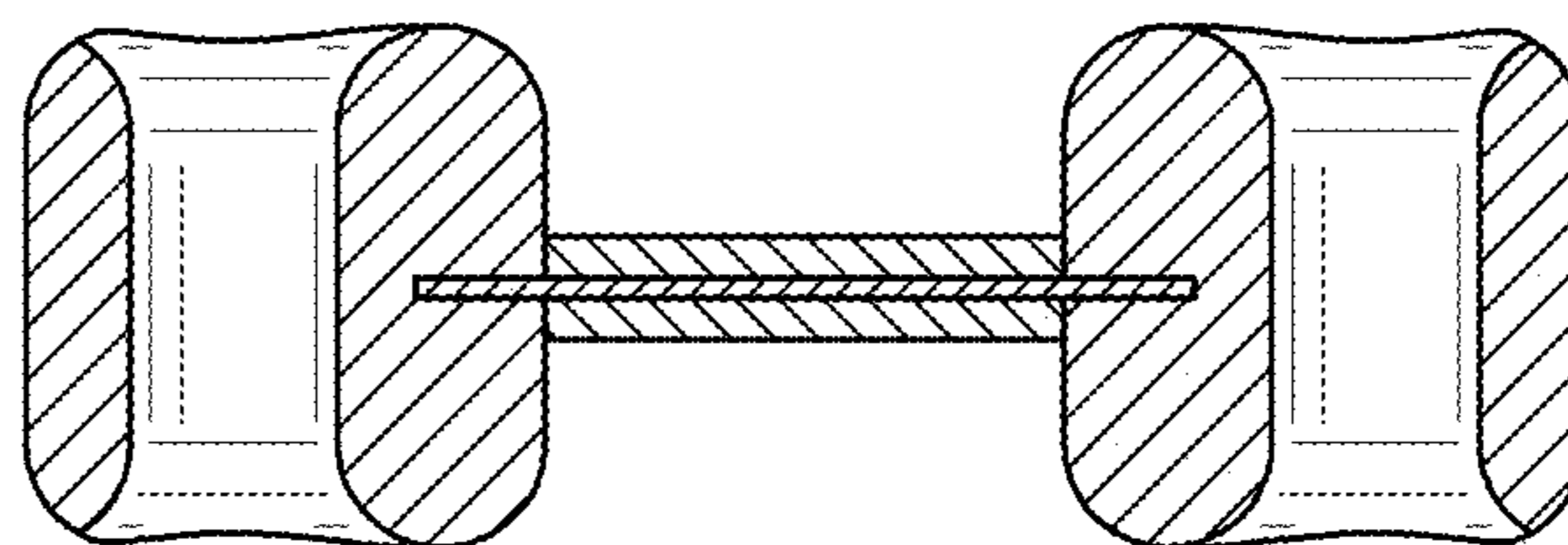


FIG.9



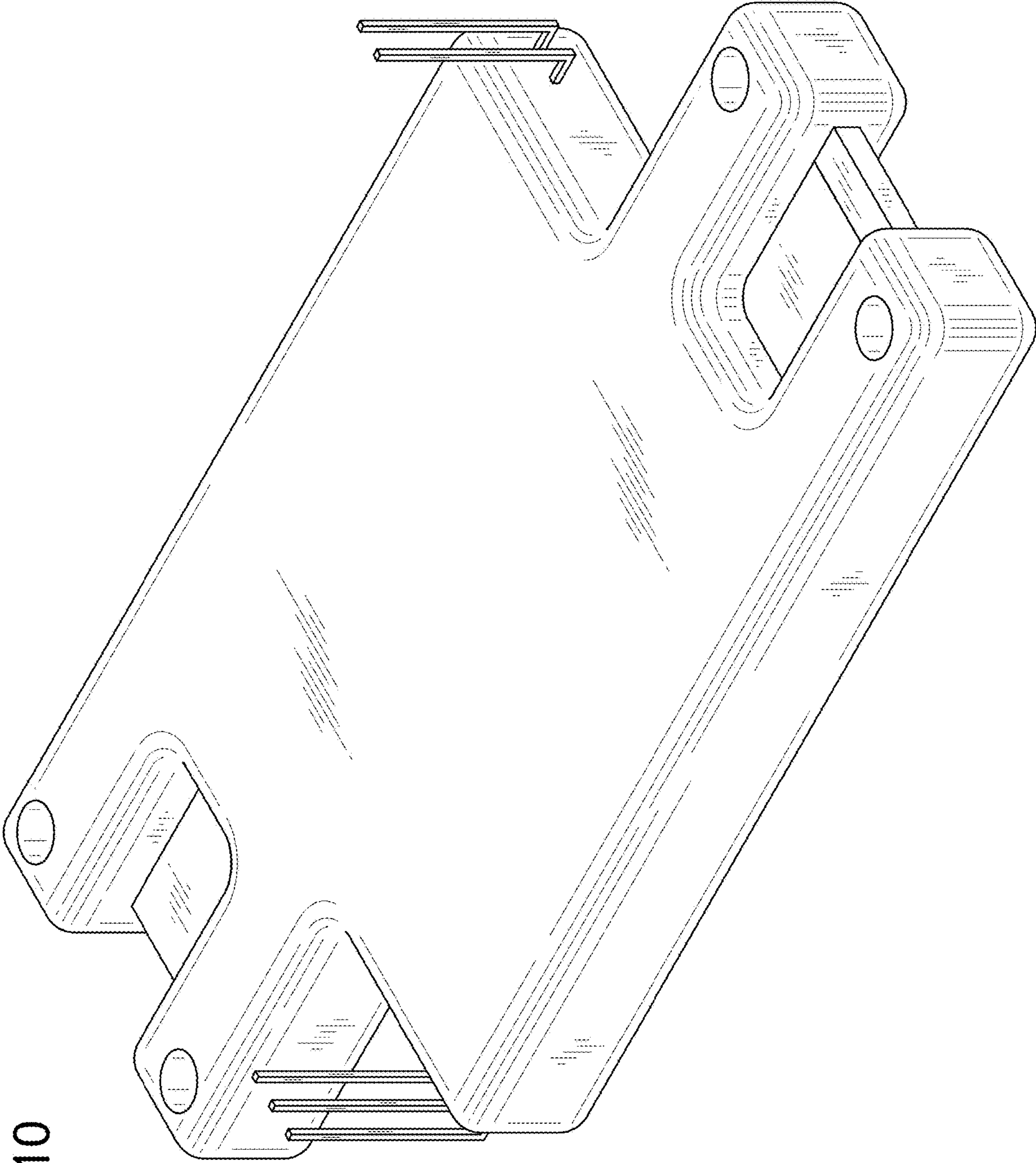


FIG.10

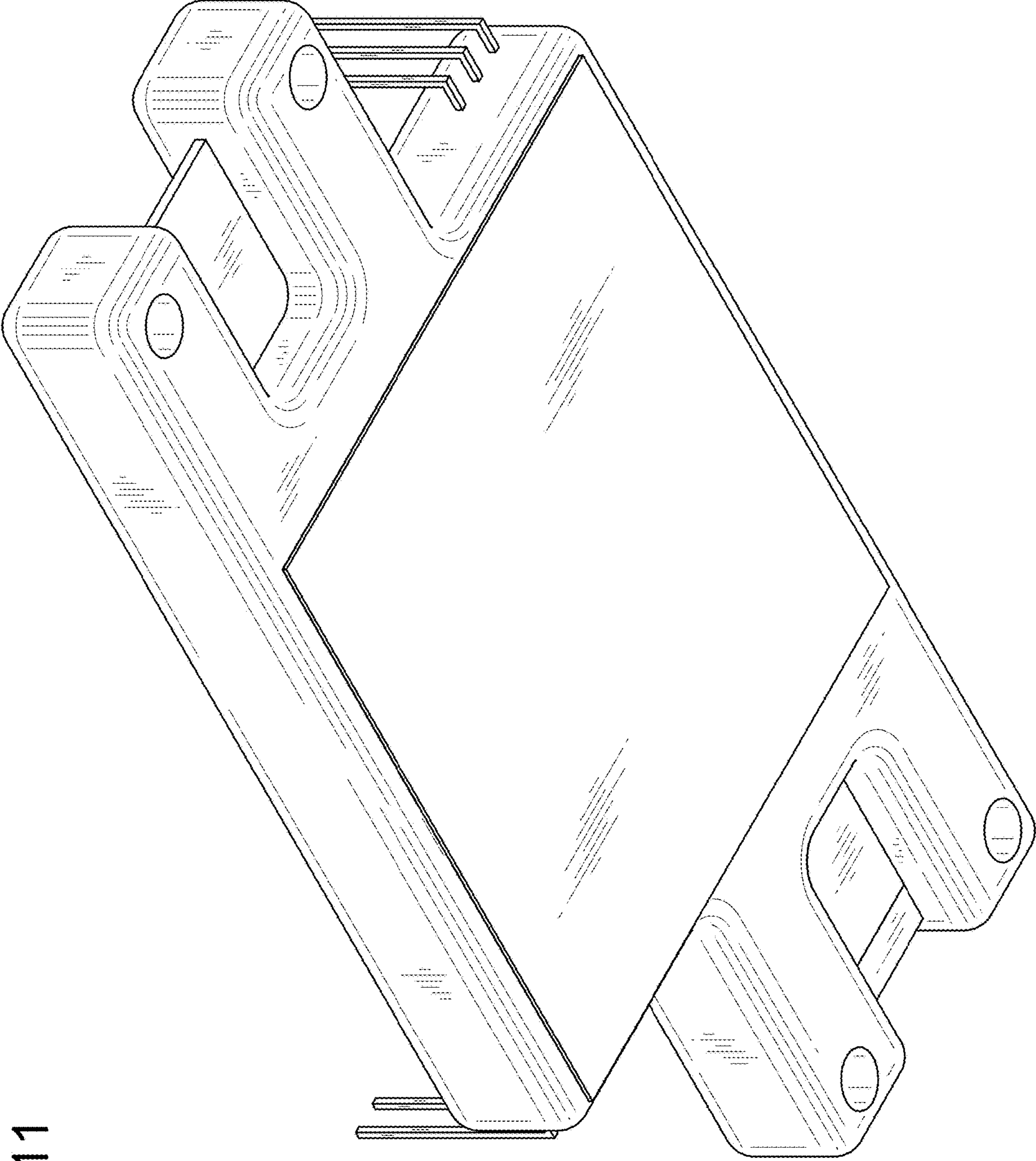


FIG.11

FIG.12

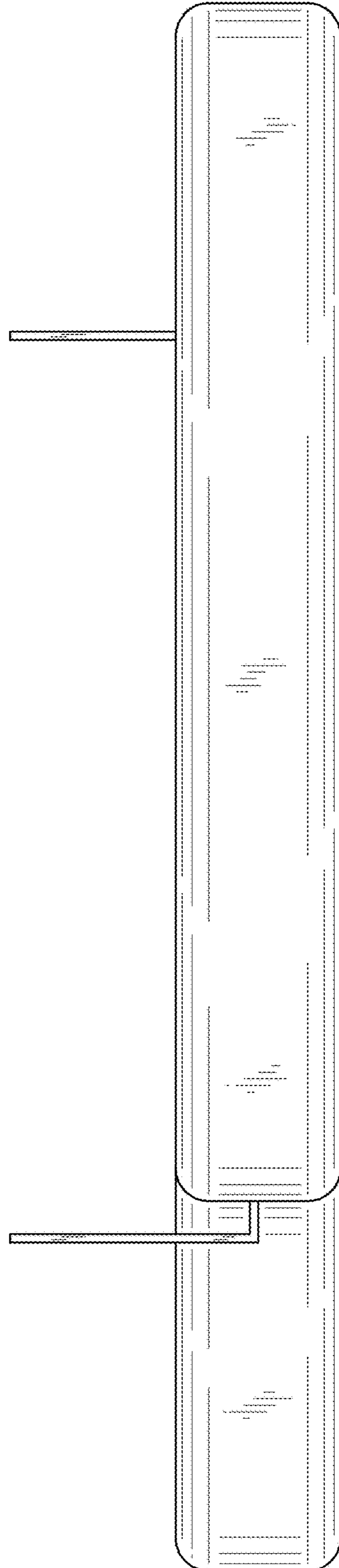
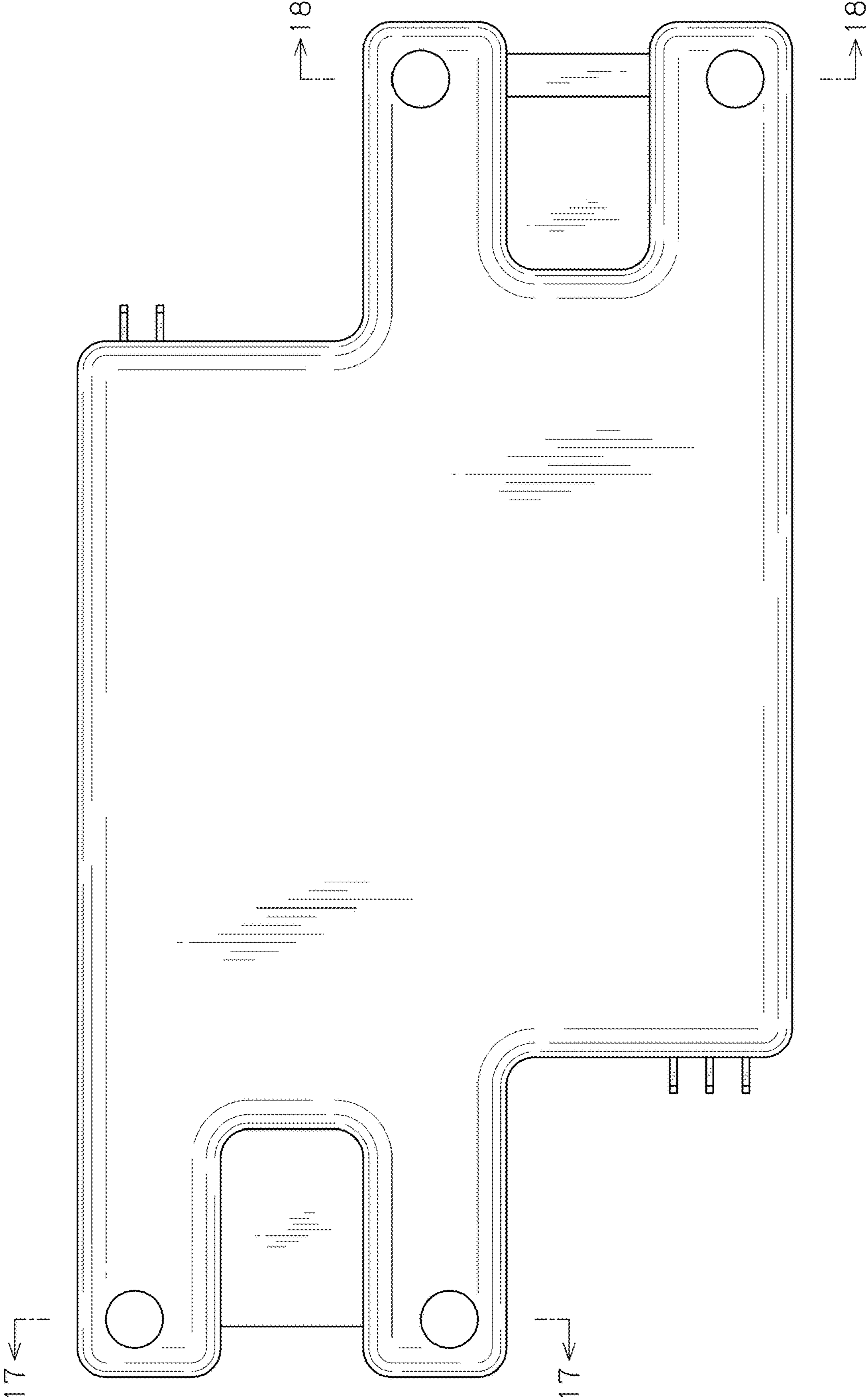


FIG.13



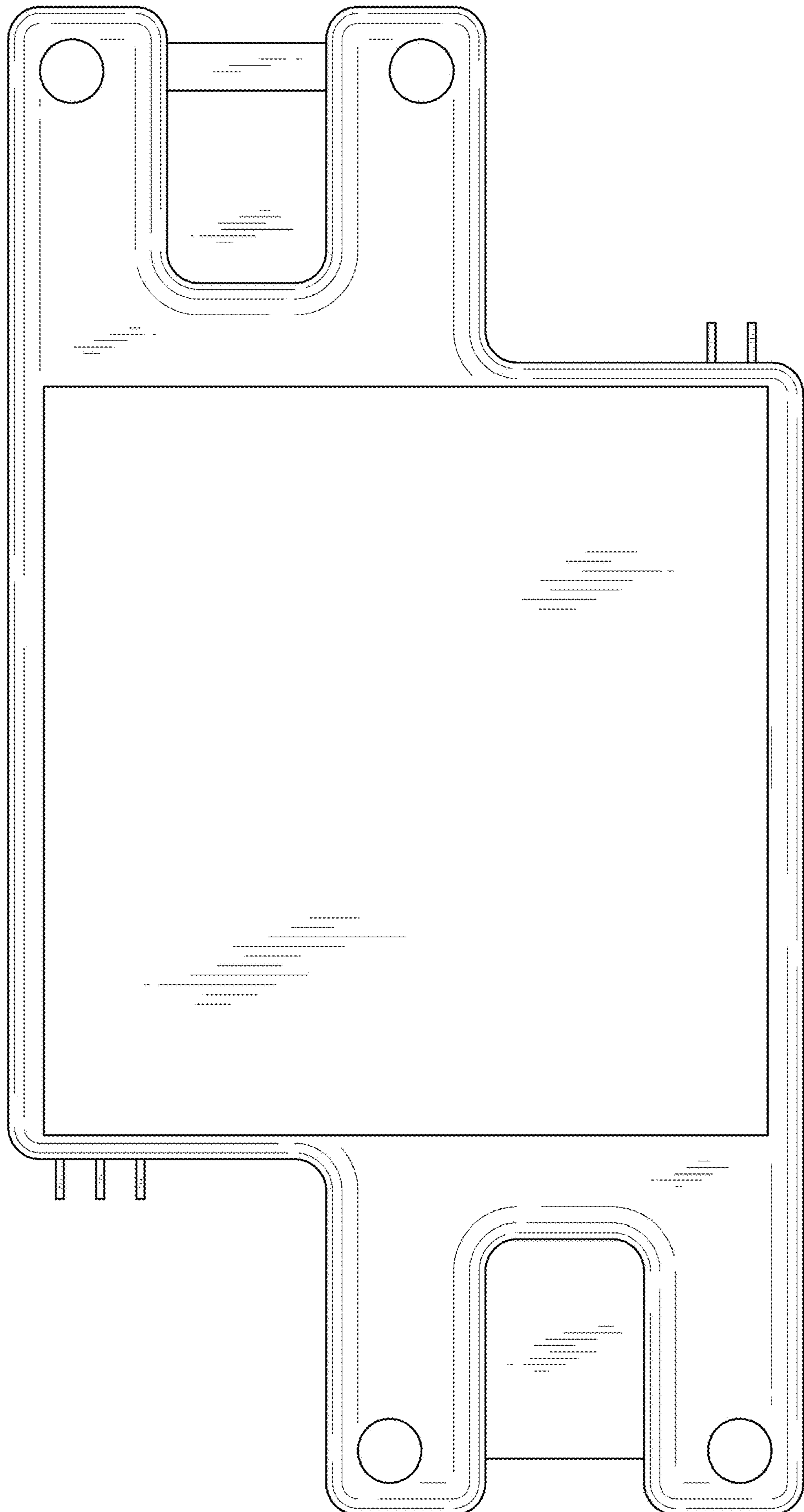


FIG.14

FIG. 15

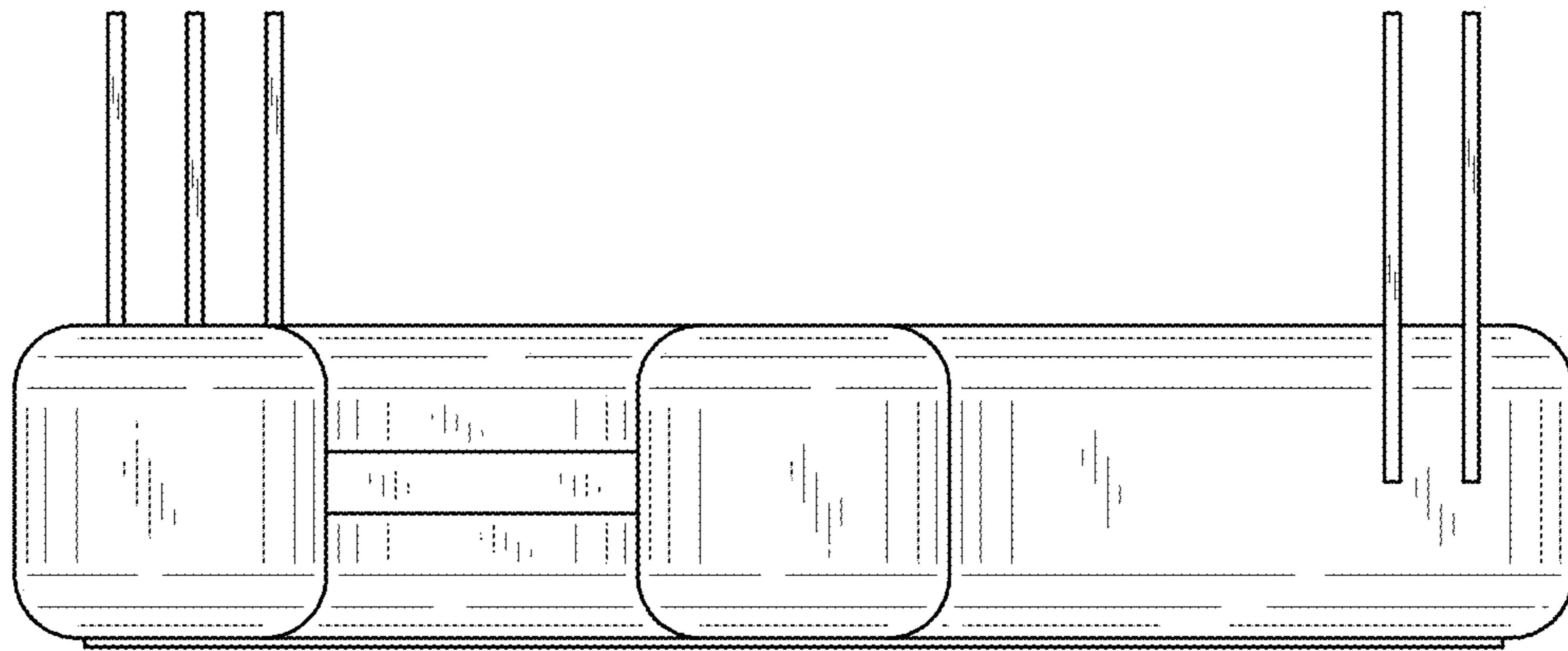


FIG. 16

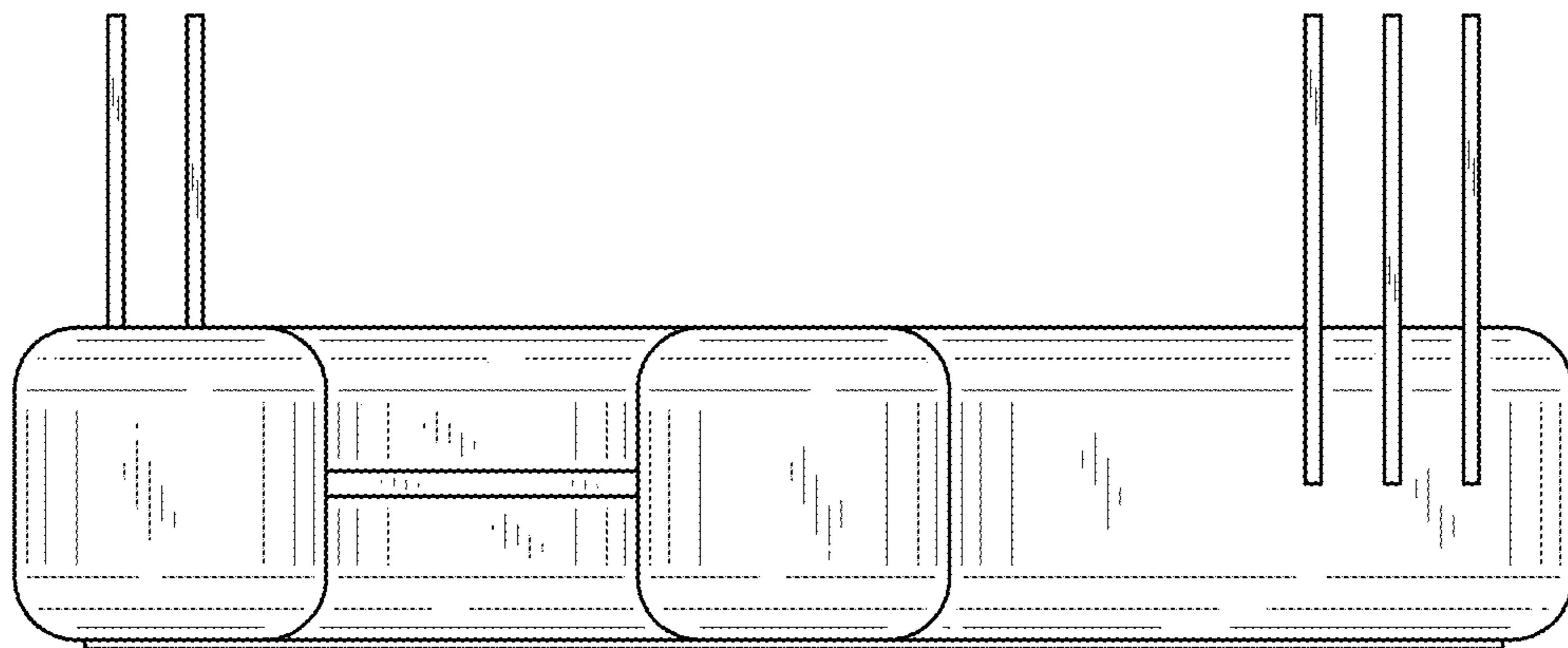


FIG.17

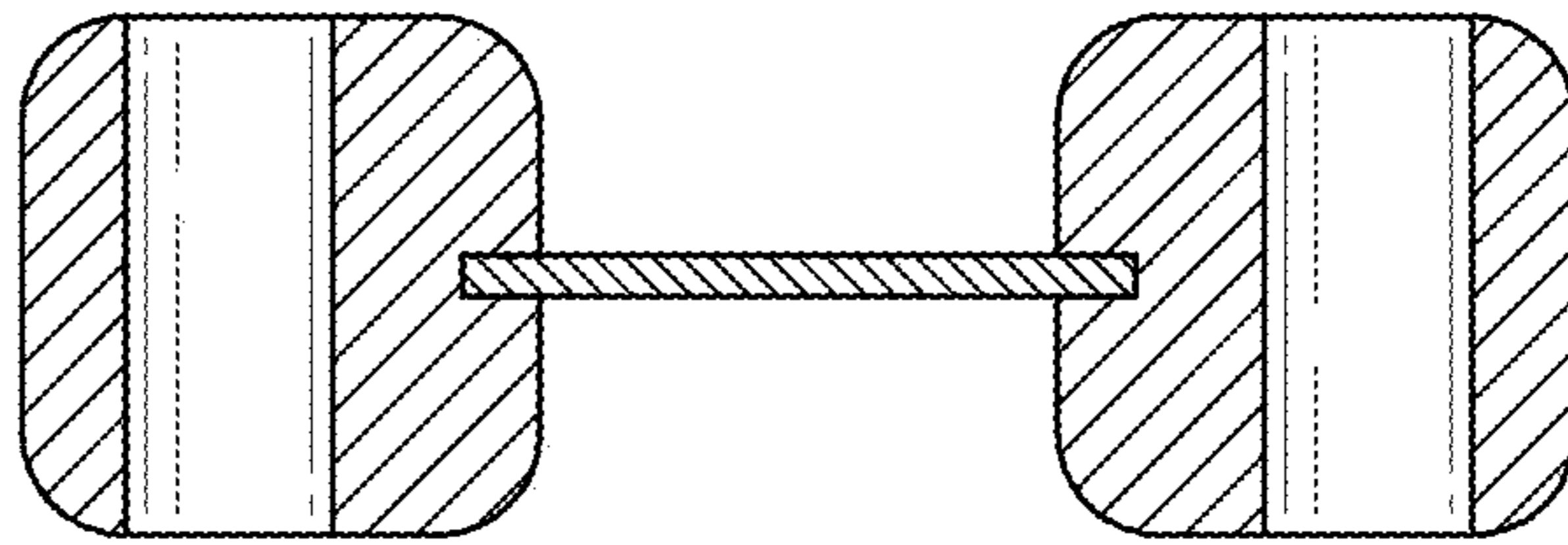


FIG.18

